SiDR608DP

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Vishay Siliconix

RoHS COMPLIANT

HALOGEN

FREE



Top View

Bottom View

| PRODUCT SUMMARY | | | | | | |
|--|---------|--|--|--|--|--|
| V _{DS} (V) | 45 | | | | | |
| $R_{DS(on)}$ max. (Ω) at V_{GS} = 10 V | 0.00120 | | | | | |
| $R_{DS(on)}$ max. (Ω) at V_{GS} = 4.5 V | 0.00180 | | | | | |
| Q _g typ. (nC) | 50.5 | | | | | |
| I _D (A) ^a | 208 | | | | | |
| Configuration | Single | | | | | |

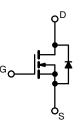
FEATURES

N-Channel 45 V (D-S) MOSFET

- TrenchFET[®] Gen IV power MOSFET
- 45 V Drain-source break-down voltage
- Tuned for low Q_q and Q_{oss}
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Synchronous rectification
- High power density DC/DC
- Motor drive control



N-Channel MOSFET

ORDERING INFORMATION

| Package | PowerPAK SO-8DC |
|---------------------------------|------------------|
| Lead (Pb)-free and halogen-free | SiDR608DP-T1-RE3 |

| ABSOLUTE MAXIMUM RATINGS | (T _A = 25 °C, unless | s otherwise noted | (k | |
|--|---------------------------------|-----------------------------------|----------------------|-----|
| PARAMETER | SYMBOL | LIMIT | UNIT | |
| Drain-source voltage | | V _{DS} | 45 | V |
| Gate-source voltage | | V _{GS} | +20, -16 | v |
| | T _C = 25 °C | | 208 | |
| Continuous drain current ($T_J = 150 \ ^\circ C$) | T _C = 70 °C | | 166 | |
| | T _A = 25 °C | I _D | 51 ^{b, c} | |
| | T _A = 70 °C | | 40.8 ^{b, c} | ^ |
| Pulsed drain current (t = 100 µs) | | I _{DM} | 400 | — A |
| Continuous source drain diade surrent | T _C = 25 °C | | 94.5 | |
| Continuous source-drain diode current | T _A = 25 °C | I _S | 5.6 ^{b, c} | |
| Single pulse avalanche current L = 0.1 mH | | I _{AS} | 50 | |
| Single pulse avalanche Energy | | E _{AS} | 125 | mJ |
| | T _C = 25 °C | | 104 | |
| Maximum power dissipation | T _C = 70 °C | | 66.6 | w |
| | T _A = 25 °C | P _D | 6.25 ^{b, c} | vv |
| | T _A = 70 °C | | 4 ^{b, c} | |
| Operating junction and storage temperature range | | T _J , T _{stg} | -55 to +150 | °C |
| Soldering recommendations (peak temperature) ^{d, e} | | | 260 | |

THERMAL RESISTANCE RATINGS

| PARAMETER | | SYMBOL | TYPICAL | MAXIMUM | UNIT |
|---|--------------|-------------------|---------|---------|------|
| Maximum junction-to-ambient ^{b, f} | t ≤ 10 s | R _{thJA} | 15 | 20 | |
| Maximum junction-to-case (drain) | Steady state | R _{thJC} | 0.9 | 1.2 | °C/W |
| Maximum junction-to-case (source) | Steady state | R _{thJC} | 1.1 | 1.4 | |

Notes

a. Based on $T_{\rm C} = 25 \ ^{\circ}{\rm C}$

b. Surface mounted on 1" x 1" FR4 board

t = 10 sC.

d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8DC is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

Rework conditions: manual soldering with a soldering iron is not recommended for leadless components e.

f. Maximum under steady state conditions is 54 °C/W

g. Package limited

| S19-0390-Rev. A, 29-Apr-2019 | |
|------------------------------|--|
|------------------------------|--|

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| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|-------------------------|--|----------|---------|---------|-------|
| Static | | | <u> </u> | • | | |
| Drain-source breakdown voltage | V _{DS} | $V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$ | 45 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | I _D = 10 mA | - | 29 | - | |
| V _{GS(th)} temperature coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = 250 μA | - | -5.8 | - | mV/°C |
| Gate-source threshold voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$ | 1.1 | - | 2.3 | V |
| Gate-source leakage | I _{GSS} | $V_{DS} = 0 V, V_{GS} = +20, -16 V$ | - | - | ± 100 | nA |
| 7 | | $V_{DS} = 45 \text{ V}, V_{GS} = 0 \text{ V}$ | - | - | 1 | |
| Zero gate voltage drain current | IDSS | $V_{DS} = 45 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$ | - | - | 10 | μA |
| On-state drain current ^a | I _{D(on)} | $V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$ | 50 | - | - | Α |
| | | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$ | - | | | 0 |
| Drain-source on-state resistance ^a | R _{DS(on)} | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$ | - | 0.00136 | 0.00180 | Ω |
| Forward transconductance a | g _{fs} | $V_{DS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$ | - | 120 | - | S |
| Dynamic ^b | • | | <u> </u> | | | |
| Input capacitance | C _{iss} | | - | 8900 | - | |
| Output capacitance | C _{oss} | | - | 1244 | - | pF |
| Reverse transfer capacitance | C _{rss} | $V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$ | - | 120 | - | |
| C _{rss} /C _{iss} ratio | | | - | 0.0135 | 0.0270 | - |
| T | Qg | $V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$ | - | 111 | 167 | |
| Total gate charge | | | - | 50.5 | 76 | |
| Gate-source charge | Q _{gs} | $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$ | - | 26 | - | nC |
| Gate-drain charge | Q _{gd} | | - | 7.8 | - | - |
| Output charge | Q _{oss} | $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ | - | 59 | - | |
| Gate resistance | Rg | f = 1 MHz | 0.3 | 0.88 | 1.5 | Ω |
| Turn-on delay time | t _{d(on)} | | - | 19 | 38 | |
| Rise time | tr | $V_{DD} = 20 \text{ V}, \text{ R}_{L} = 1 \Omega$ | - | 10 | 20 | |
| Turn-off delay time | t _{d(off)} | $I_D \cong 20$ Å, $V_{GEN} = 10$ V, $R_g = 1$ Ω | - | 50 | 100 | |
| Fall time | t _f | | - | 8 | 16 | |
| Turn-on delay time | t _{d(on)} | | - | 52 | 104 | ns |
| Rise time | t _r | $V_{DD} = 20 \text{ V}, \text{ R}_{\text{I}} = 1 \Omega$ | - | 86 | 172 | |
| Turn-off delay time | t _{d(off)} | $I_D \cong 20 \text{ Å}, V_{\text{GEN}} = 4.5 \text{ V}, \text{R}_\text{g} = 1 \Omega$ | - | 50 | 100 | |
| Fall time | t _f | | - | 25 | 50 | |
| Drain-Source Body Diode Characteristic | s | | <u> </u> | • | | |
| Continuous source-drain diode current | I _S | T _C = 25 °C | - | - | 94.5 | |
| ulse diode forward current ($t_p = 100 \ \mu s$) I_{SM} | | | - | - | 400 | A |
| Body diode voltage | V _{SD} | I _S = 10 A | - | 0.7 | 1.1 | V |
| Body diode reverse recovery time | t _{rr} | - | - | 52 | 104 | ns |
| Body diode reverse recovery charge | Q _{rr} | I _F = 10 A, di/dt = 100 A/μs, | - | 71 | 142 | nC |
| Reverse recovery fall time | t _a | $T_{\rm J} = 25 \ ^{\circ}{\rm C}$ | - | 32 | - | |
| Reverse recovery rise time | t _b | | - | 20 | _ | ns |

Notes

a. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%$

b. Guaranteed by design, not subject to production testing

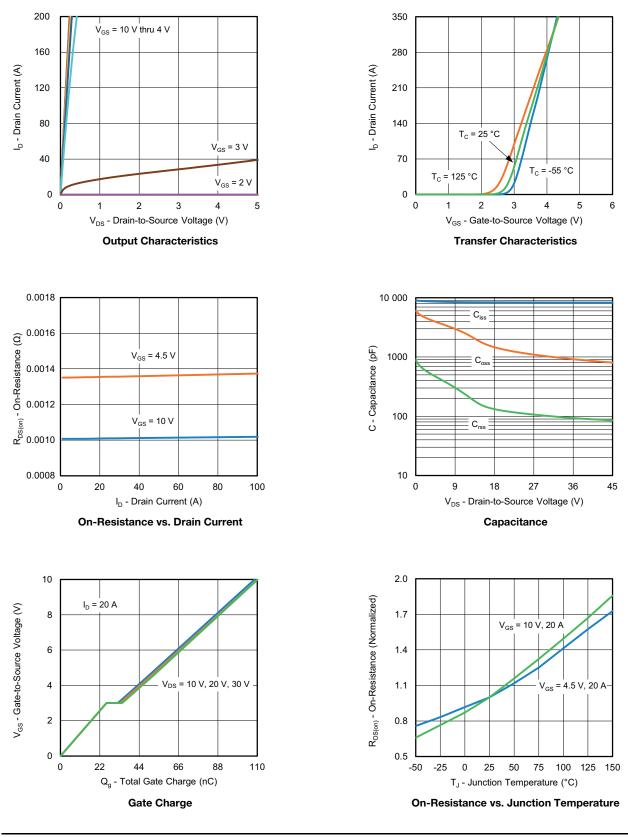
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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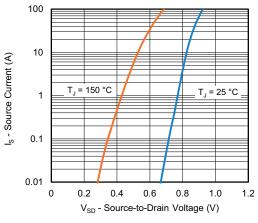
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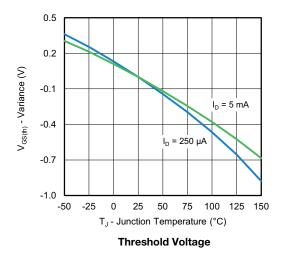
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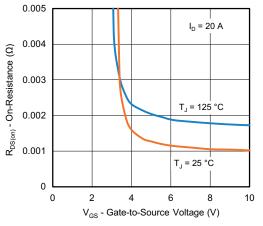
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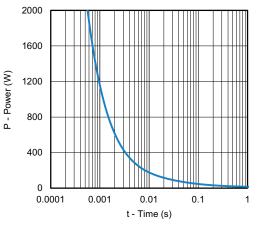


Source-Drain Diode Forward Voltage





On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

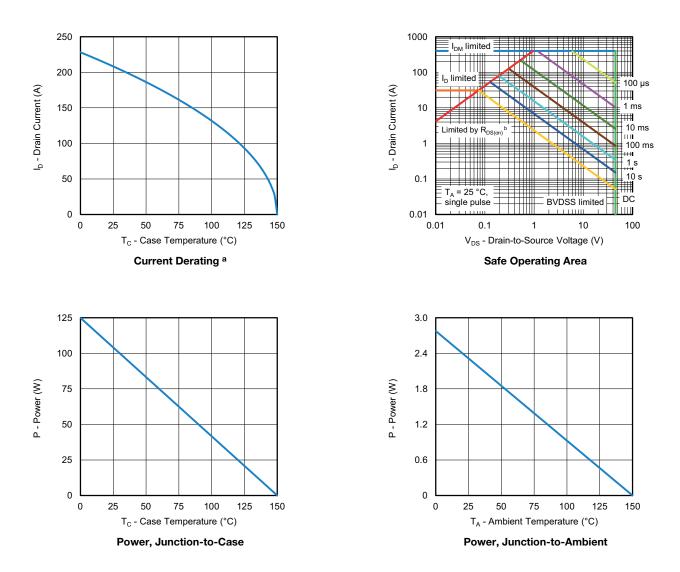
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Notes

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

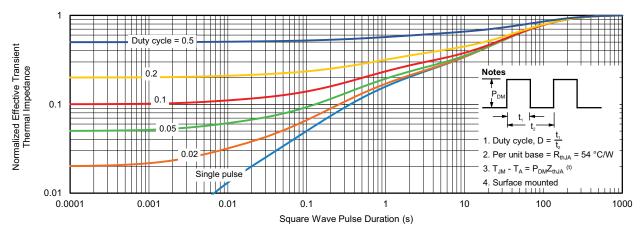
b. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

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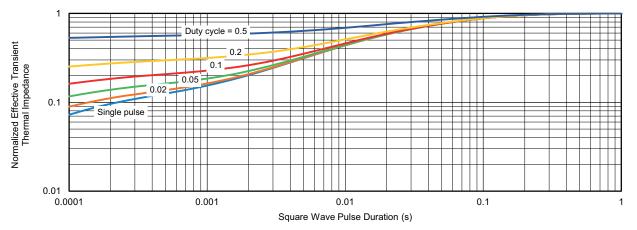


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



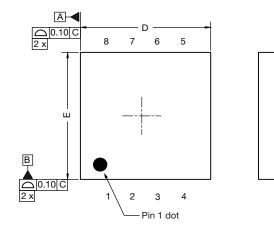
Normalized Thermal Transient Impedance, Junction-to-Case

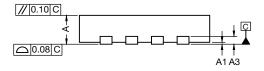
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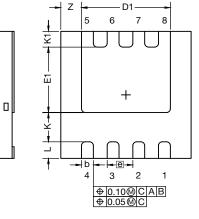


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Case Outline for PowerPAK® 1212-SWLH







| DIM. | | MILLIMETERS | | | INCHES | | | |
|---------------|---------------------|-------------|------|------------|------------|-------|--|--|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. | | |
| А | 0.82 | 0.90 | 0.98 | 0.032 | 0.035 | 0.038 | | |
| A1 | 0.00 | - | 0.05 | 0.000 | - | 0.002 | | |
| A3 | | 0.20 ref. | | | 0.008 ref. | | | |
| b | 0.25 | 0.30 | 0.35 | 0.010 | 0.012 | 0.014 | | |
| D | 3.20 | 3.30 | 3.40 | 0.126 | 0.130 | 0.134 | | |
| D1 | 2.15 | 2.25 | 2.35 | 0.085 | 0.089 | 0.093 | | |
| E | 3.20 | 3.30 | 3.40 | 0.126 | 0.130 | 0.134 | | |
| E1 | 1.60 | 1.70 | 1.80 | 0.063 | 0.067 | 0.071 | | |
| е | | 0.65 bsc. | | | 0.026 bsc. | | | |
| к | 0.76 ref. | | | 0.030 ref. | | | | |
| K1 | 0.41 ref. | | | 0.016 ref. | | | | |
| L | 0.33 | 0.43 | 0.53 | 0.013 | 0.017 | 0.021 | | |
| Z | 0.525 ref. | | | 0.021 ref. | | | | |
| I: C20-0863-F | lev. B, 20-Jul-2020 | | | 1 | | | | |



RECOMMENDED MINIMUM PADS FOR PowerPAK[®] 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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